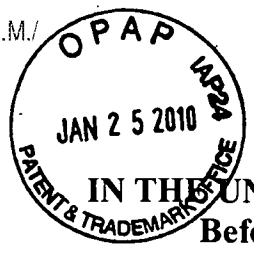


03/02/2010



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
Before the Board of Patent Appeals and Interferences**

In re Patent Application of

WONG et al.

Atty. Ref.: JSP -4593-182

Serial No. 09/741,684

TC/A.U.: 2627

Filed: December 18, 2000

Examiner: Brian E. Miller

For: BONDING PAD OF SUSPENSION CIRCUIT

\* \* \* \* \*

(January 23, 2010 = Saturday)  
(January 24, 2010 = Sunday)  
January 25, 2010 (= Monday)

Mail Stop Appeal Brief - Patents  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**REPLY BRIEF**

In response to the Examiner's Answer dated November 23, 2009, Applicant now submits the following Reply Brief pursuant to 37 C.F.R. § 41.41.